

SBR1045SP5

10A SBR[®] SUPER BARRIER RECTIFIER PowerDI[®]5

Features

- Designed as Bypass Diodes for Solar Panels
- Selectively Rated for 200°C Maximum Junction Temperature for High Thermal Reliability
- Patented Super Barrier Rectifier Technology
- Low Forward Voltage Drop
- Excellent High Temperature Stability
- Lead Free Finish, RoHS Compliant (Note 1)

Mechanical Data

- Case: PowerDI[®]5
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin annealed over Copper leadframe.
 Solderable per MIL-STD-202, Method 208 [®]
- Weight: 0.093 grams (approximate)





RIGHT PIN O BOTTOMSIDE HEAT SINK

Note: Pins Left & Right must be electrically connected at the printed circuit board.

Ordering Information (Note 2)

Part Number	Case	Packaging
SBR1045SP5-13	PowerDI [®] 5	5000/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied, see EU Directive 2002/95/EC Annex Notes
- 2. For packaging details, go to our website at http://www.diodes.com.

Marking Information



S1045S = Product Type Marking Code

Oli = Manufacturers' code marking

K = Factory designator

YYWW = Date Code Marking

YY = Last two digits of year (ex: 08 for 2008)

WW = Week code (01 - 53)



Maximum Ratings @T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _{RM}	45	٧
RMS Reverse Voltage	V _{R(RMS)}	32	V
Average Rectified Output Current	lo	10	Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	180	А
Repetitive Peak Avalanche Power (1µs, 25°C)	P _{ARM}	10,000	W

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Typical Thermal Resistance Thermal Resistance Junction to Lead Thermal Resistance Junction to Case (Note 3) Thermal Resistance Junction to Ambient (Note 3) Thermal Resistance Junction to Ambient (Note 4)	,	$egin{array}{l} R_{ hetaJL} \ R_{ hetaJA} \ R_{ hetaJA} \end{array}$	3 6 102 60	°C/W
Operating Temperature Range	$V_R \le 80\% V_{RRM}$ $V_R \le 50\% V_{RRM}$ DC Forward Mode	TJ	-65 to +150 ≤180 ≤200	°C
Storage Temperature Range		T_{STG}	-65 to +175	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

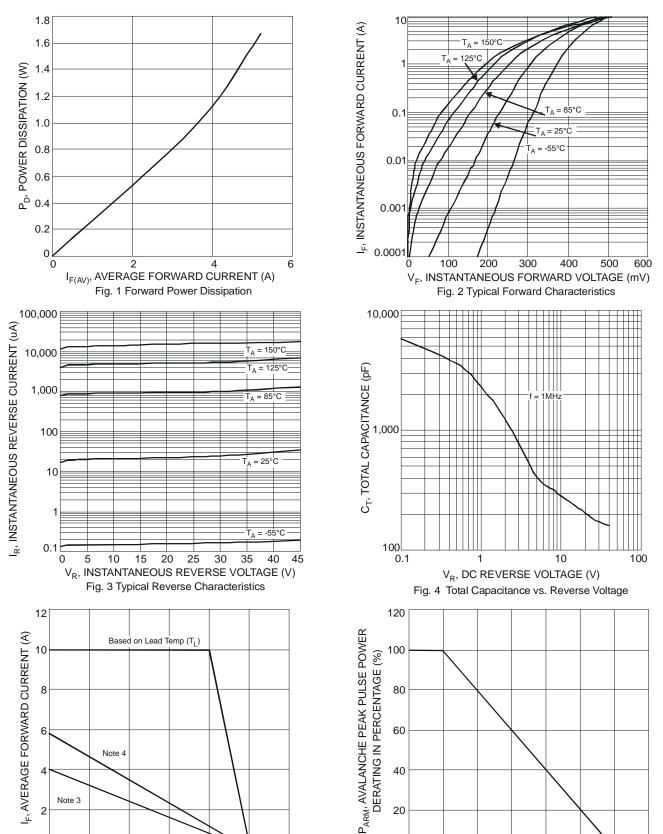
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 5)	$V_{(BR)R}$	45	-	ı	V	$I_R = 0.5 \text{mA}$
Forward Voltage Drop	V _F	-	- 0.49 0.47	0.51 0.55 0.53	V	I _F = 8A, T _J = 25°C I _F = 10A, T _J = 25°C I _F = 10A, T _J = 125°C
Leakage Current (Note 5)	I _R	-	0.03 - 17	0.45 18 100	mA	$V_R = 45V, T_J = 25^{\circ}C$ $V_R = 45V, T_J = 100^{\circ}C$ $V_R = 45V, T_J = 150^{\circ}C$

Notes:

- 3. FR-4 PCB, 2oz. Copper, minimum recommended pad layout per http://www.diodes.com.
- 4. Polymide PCB, 2oz. Copper, minimum recommended pad layout per http://www.diodes.com.
- 5. Short duration pulse test used to minimize self-heating effect.

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125

150

175

100

T_A, AMBIENT TEMPERATURE (°C)

Fig. 5 Forward Current Derating Curve

150 175

50

75

Note 3

0

25

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20

0

0

25

50

75

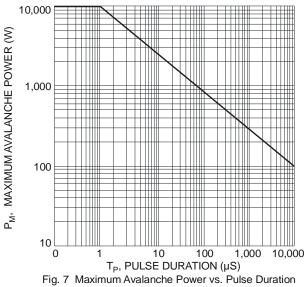
100

T_{.J}, JUNCTION TEMPERATURE (°C)

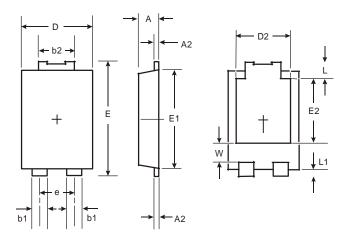
Fig. 6 Pulse Derating Curve

125



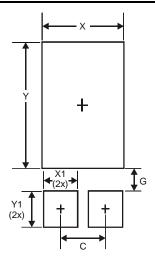


Package Outline Dimensions



PowerDI [®] 5				
Dim	Min	Max		
Α	1.05	1.15		
A2	0.33	0.43		
b1	0.80	0.99		
b2	1.70	1.88		
D	3.90	4.05		
D2	3.054 Typ			
E	6.40	6.60		
е	1.84 Typ			
E1	5.30	5.45		
E2	3.549 Typ			
L	0.75	0.95		
L1	0.50	0.65		
W	1.10	1.41		
All Dimensions in mm				

Suggested Pad Layout



Dimensions	Value (in mm)
С	1.840
G	0.852
Х	3.360
X1	1.390
Y	4.860
Y1	1.400

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